

Course Content

Course Title (English)	System in Package
Course Title (Chinese)	晶片系統封裝
Credit	3
Instructor	Prof. Hsin-Chia Lu 盧信嘉 教授
Outline	<p>Scopes: Semiconductor IC Packaging/Testing/Assembly/Reliability Basics, Substrates for Embedded Passives, Electrical/Thermal/Stress Analysis, Applications of System in Package..</p> <p>Contents:</p> <ol style="list-style-type: none">1. Introduction to electronic packaging2. Flip-chip, stacked, 3D packages, CBGA (ceramic ball grid array) and CCGA (ceramic column grid array)3. Technology trend of advanced semiconductor packaging4. Electrical design/analysis of system in package5. Thermal/Stress analysis of system in package6. Testing/Reliability of system in package7. IPD (Integrated Passive Devices)8. Applications of system in package
Goal	<p>Understand different materials and processing flows for package manufacturing.</p> <p>Design of electronics packaging.</p> <p>Understand thermal and reliability issues in package.</p>
English Teaching	<input type="checkbox"/> YES <input checked="" type="checkbox"/> NO

Teaching
Material

English

Chinese